

Roth Elektronik® FR4 Boards – Safety Information Sheet

Trade Name: **Epoxy Resin FR4**
 DIN IEC 249 Copper-clad Epoxy Resin Glass Fibre Boards

This information sheet compiles some data from the safety data sheets of the base materials manufacturers. Should you require further information, please contact the respective manufacturer. All base materials used comply with the relevant DIN standards and are UL-listed. For its products, Roth Elektronik® uses base materials provided by various manufacturers, but all made to the same standards.

Here is a list of some base materials manufacturers:

Company	Manufacturers of Board Base Materials	
1	ISOLA AG D-52348 Düren / Germany	http://www.isola.de
2	DOOSAN ELECTRO - MATERIALS Korea	http://www.dse.co.kr
3	Matsushita Electric Works Deutschland GmbH Japan	http://www.matsushita.de

Subject	Description	
1. Chemical composition	Laminated fabric made of glass fabric and cured, brominated epoxy resin, one or both sides clad with copper foil	
2. Composition/ components	Glass fabric:	E-glass
	Resin matrix:	Brominated epoxy resin based on tetrabromobisphenol (TBBA)#TBBPA
3. Hazards	No personal or environmental hazards need be feared if used and stored in accordance with the regulations.	
4. First-aid measures	If cuts or scratches are caused by the material, thoroughly clean the wound with water and soap and disinfect it. If in doubt about how to treat the wound, consult a doctor.	
5. Fire-fighting measures	Extinguishing agents: suitable: any, if possible, don't use water Dangerous conflagration gases: depending on the fire conditions, the following may be generated: carbon monoxide, carbon dioxide, hydrogen bromide and organic bromine compounds	
6. Measures in case of unintentional release	n/a	

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7. Handling and storage	Store in a dry place; take precautions against dust explosion if processed mechanically in an extraction system processing.																																																																
8. Exposure limitation and personal protective equipment	Limit values: <table><tr><td>CAS number</td><td>Substance</td><td>Kind</td><td>Value</td><td>Unit</td></tr><tr><td>n/a</td><td></td><td></td><td></td><td></td></tr></table> Personal protective equipment: recommended for mechanical treatment - Respiratory equipment: extraction - Hand protection: protective skin ointment - Eye protection: advisable - Body protection: n/a - Hygiene precautions: Cleanness required, don't smoke eat or drink at the working place.					CAS number	Substance	Kind	Value	Unit	n/a																																																						
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9. Physical and chemical properties	<table><tr><td>Form:</td><td></td><td></td><td>boards</td></tr><tr><td>Colour/smell:</td><td></td><td></td><td>yellowish (resin matrix) / none</td></tr><tr><td>Change of state:</td><td></td><td></td><td></td></tr><tr><td>- Boiling point:</td><td>(C°)</td><td></td><td>n/a</td></tr><tr><td>- Melting point:</td><td>(C°)</td><td></td><td>n/a</td></tr><tr><td>Glass transition temperature:</td><td>(C°)</td><td></td><td>approx. >130°C (DSC method 20°C/min heating-up rate)</td></tr><tr><td>Flash point:</td><td>(C°)</td><td></td><td>n/a</td></tr><tr><td>Inflammation temperature:</td><td>(C°)</td><td></td><td>n/a</td></tr><tr><td>Explosibility limit:</td><td>(% by vol.)</td><td></td><td>lower not determined, dust explosion hazard upper not determined from approx. 300°C thermogravimetry (10°C/min heating-up rate)</td></tr><tr><td>Pyrolysis:</td><td>(C°)</td><td></td><td></td></tr><tr><td>Vapour pressure:</td><td>(mbar)</td><td></td><td>n/a at 20°C</td></tr><tr><td>Density:</td><td>(g/cm³)</td><td></td><td>approx. 1.8 at 20°C</td></tr><tr><td>Bulk density:</td><td>(kg/m³)</td><td></td><td>n/a</td></tr><tr><td>Viscosity:</td><td>(mPa*s)</td><td></td><td>n/a</td></tr><tr><td>Solubility in water:</td><td></td><td></td><td>insoluble</td></tr></table>					Form:			boards	Colour/smell:			yellowish (resin matrix) / none	Change of state:				- Boiling point:	(C°)		n/a	- Melting point:	(C°)		n/a	Glass transition temperature:	(C°)		approx. >130°C (DSC method 20°C/min heating-up rate)	Flash point:	(C°)		n/a	Inflammation temperature:	(C°)		n/a	Explosibility limit:	(% by vol.)		lower not determined, dust explosion hazard upper not determined from approx. 300°C thermogravimetry (10°C/min heating-up rate)	Pyrolysis:	(C°)			Vapour pressure:	(mbar)		n/a at 20°C	Density:	(g/cm³)		approx. 1.8 at 20°C	Bulk density:	(kg/m³)		n/a	Viscosity:	(mPa*s)		n/a	Solubility in water:			insoluble
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11. Toxicity	Dust formed during mechanical processing is basically not toxic. However, beginners may experience skin irritation, but will quickly get accustomed. In rare cases, skin allergies may occur. If it does, the affected worker needs to be employed in another place.																																																																

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